

| <b>'147 Patent Claim Mapping Table</b>                                                                                                                                                                                                                 |                                                                                                                                                                                                                                                         |                                                                                                                                                                                                                                                                                             |                                                                                                                                                                                                                                                                                                         |
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| 1[pre]: A wearable electronic device comprising:                                                                                                                                                                                                       | 10[pre]: A method for forming a wearable electronic device comprising:                                                                                                                                                                                  | 18[pre]: A wearable electronic device configured to be worn on a finger comprising:                                                                                                                                                                                                         | 21[pre]: A wearable electronic device configured to be worn on a finger comprising:                                                                                                                                                                                                                     |
| 1[a]: a body part made of a material, having an inner surface and an outer surface,                                                                                                                                                                    | 10[a]: providing a body part made of a material, having an inner surface and an outer surface,                                                                                                                                                          | 18[a]: a C-shaped body part made of a material, having an inner surface and an outer surface,                                                                                                                                                                                               | 21[a]: an external portion made of a first material and having an inner surface and an outer surface, wherein the outer surface of the external portion defines an exterior surface of the electronic device;                                                                                           |
| 1[b]: wherein a cavity is formed on the inner surface of the body part, the cavity extending from the inner surface of the body part towards the outer surface of the body part and having a depth arranged within the inner surface of the body part, | 10[b]: wherein a cavity is formed on the inner surface of the body part, the cavity extending from the inner surface of the body part towards the outer surface of the body part and having a depth arranged within the inner surface of the body part, | 18[b]: wherein a cavity is formed on the inner surface of the C-shaped body part, the cavity extending from the inner surface of the C-shaped body part towards the outer surface of the C-shaped body part and having a depth arranged within the inner surface of the C-shaped body part; | 21[b]: an interior portion coupled to the external portion, wherein the interior portion is disposed below the inner surface of the external portion, wherein the interior portion is made of a second material, and wherein the interior portion defines an interior surface of the electronic device; |

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| 1[c]: an electronic part arranged in the cavity, wherein at least a portion of the electronic part has a thickness that is less than the depth of the cavity, and | 10[c]: disposing an electronic part arranged in the cavity, wherein at least a portion of the electronic part has a thickness that is less than the depth of the cavity, and | 18[c]: an electronic part arranged in the cavity, wherein at least a portion of the electronic part has a thickness that is less than the depth of the cavity, wherein the electronic part comprises:                                                                      | 21[c]: an electronic part disposed within the interior portion, wherein the electronic part comprises:                                                                                                                                                                                                                             |
|                                                                                                                                                                   |                                                                                                                                                                              | 18[d]: a flexible printed circuit board having an electronic component disposed thereon,                                                                                                                                                                                   | 21[d]: a rigid-flex printed circuit board comprising at least a first rigid circuit board and a second rigid circuit board coupled via a flexible material; and                                                                                                                                                                    |
|                                                                                                                                                                   |                                                                                                                                                                              | 18[e]. wherein the electronic component is selected from a group consisting of: an infrared transmitter, a microcontroller, a radio frequency transceiver, a temperature sensor and an infrared receiver, and a battery coupled to the flexible printed circuit board; and | 21[e]: at least one electronic component disposed upon the first rigid printed circuit board, wherein the electronic component is selected from a group consisting of: a light emitting diode (LED), a microcontroller, a temperature sensor, a light sensor, an accelerometer, a wireless interface and a haptic feedback device. |

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| 1[d]: a coating made of a potting material on the inner surface of the body part, covering the electronic part and the cavity.                                                                                      | 10[d]: disposing a coating made of a potting material on the inner surface of the body part, covering the electronic part and the cavity.                                                                                   | 18[f]: a coating made of a potting material on the inner surface of the body part, covering the electronic part and the cavity.                                                                                                                 |                                                                                                                                                                                                                                                                    |
| 2: The wearable electronic device according to claim 1, wherein the material is a titanium material.                                                                                                                | 11: The method according to claim 10, wherein the material is selected from a group consisting of: titanium, titanium alloy, steel, platinum, gold, silver, aluminum, polymer, plastic, tungsten carbide and a metal alloy. | 19: The wearable electronic device according to claim 18, wherein the material is selected from a group consisting of: titanium, titanium alloy, steel, platinum, gold, silver, aluminum, polymer, plastic, tungsten carbide and a metal alloy. | 22[a]: The wearable electronic device according to claim 21, wherein the first material is selected from a group consisting of: titanium, titanium alloy, stainless steel, platinum, gold, silver, aluminum, polymer, plastic, tungsten carbide and a metal alloy; |
| 3: The wearable electronic device according to claim 1, wherein the material is selected from a group consisting of: steel, platinum, gold, silver, aluminum, polymer, plastic, tungsten carbide and a metal alloy. |                                                                                                                                                                                                                             |                                                                                                                                                                                                                                                 |                                                                                                                                                                                                                                                                    |

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| 4: The wearable electronic device according to claim 1, wherein the electronic part is disposed proximate to a bottom of the cavity.                                           | 12: The method according to claim 10, wherein the electronic part is disposed proximate to a bottom of the cavity, and wherein the electronic part comprises a circuit board selected from a group consisting of: a rigid-flexible printed circuit board, a flexible printed circuit board. |                                                                                                                                                                                  |                                                                                                                                  |
| 5: The wearable electronic device according to claim 1, wherein the potting material is selected from a group consisting of: epoxy material, silicone, a resin, and a polymer. | 13: The method according to claim 10, wherein the potting material is selected from a group consisting of: epoxy material, silicone, a resin, and a polymer.                                                                                                                                | 20: The wearable electronic device according to claim 18, wherein the potting material is selected from a group consisting of: epoxy material, silicone, a resin, and a polymer. | 22[b]: and wherein the second material is selected from a group consisting of: epoxy material, silicone, a resin, and a polymer. |

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| 6: The wearable electronic device according to claim 1, wherein the electronic part is selected from a group consisting of: a battery, an infrared transmitter, a microcontroller, a radio frequency transceiver, a temperature sensor, a haptic feedback device, a piezo actuator, and an infrared receiver. | 14: The method according to claim 10, wherein the electronic part is selected from a group consisting of: a battery, an infrared transmitter, a microcontroller, a radio frequency transceiver, a temperature sensor, a haptic feedback device, a piezo actuator, and an infrared receiver. |  |  |
| 7: The wearable electronic device according to claim 1, wherein the electronic part comprises a circuit board selected from a group consisting of: a rigid-flexible printed circuit board, a flexible printed circuit board.                                                                                  |                                                                                                                                                                                                                                                                                             |  |  |
|                                                                                                                                                                                                                                                                                                               | 15: The method according to claim 14, wherein the potting material comprises a clear material and an opaque material.                                                                                                                                                                       |  |  |

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| 8: The wearable electronic device according to claim 1, wherein the body part comprises a ring configured to be worn on a finger.         | 16: The method according to claim 10, wherein the body part comprises a ring configured to be worn on a finger.         |  |  |
| 9: The wearable electronic device according to claim 1, wherein the electronic part comprises an electromagnetic induction charging coil. | 17: The method according to claim 10, wherein the electronic part comprises an electromagnetic induction charging coil. |  |  |